WHAT IS CLAIMED IS:

1. A DC block circuit comprising:

a conductive line disposed on one surface of a dielectric substrate;

an interdigital capacitor forming a part of said conductive line; and

a chip capacitor that is disposed so that said interdigital capacitor is sandwiched between said chip capacitor and said dielectric substrate.

2. The DC block circuit according to Claim 1, further comprising connectors on both ends of said conductive line.

3. The DC block circuit according to Claim 1, wherein said conductive line, said interdigital capacitor, and said chip capacitor have substantially equal widths.

4. The DC block circuit according to Claim 1, wherein said chip capacitor has a width greater than that of said conductive line.

5. The DC block circuit according to Claim 1, wherein said interdigital capacitor has a width greater than that of said conductive line.

6. The DC block circuit according to Claim 1, wherein said interdigital capacitor is coated with a resist film constructed of an insulator.

7. The DC block circuit according to Claim 1, wherein a microstripline including a ground conductor formed on another surface of said dielectric substrate is constructed.

8. The DC block circuit according to Claim 1, wherein a coplanar line including a ground conductor formed on the surface of said dielectric substrate is constructed.

9. The DC block circuit according to Claim 1, wherein a grounded coplanar line including two ground conductors respectively formed on the surface and another surface of said dielectric substrate is constructed.

10. Communication equipment comprising:

a DC block circuit including a conductive line disposed on one surface of a dielectric substrate, an interdigital capacitor forming a part of said conductive line, and a chip capacitor that is disposed so that said interdigital capacitor is sandwiched between said chip capacitor and said dielectric substrate;

a first electric circuit connected to an end of said DC block circuit; and

a second electric circuit connected to another end of said DC block circuit, said second electric circuit having a bias supply voltage different from that of said first electric circuit.

11. The communication equipment according to Claim 10, wherein said DC block circuit further includes connectors on both ends of said conductive line.

12. The communication equipment according to Claim 10, wherein said conductive line, said interdigital capacitor, and said chip capacitor have substantially equal widths.

13. The communication equipment according to Claim 10, wherein said chip capacitor has a width greater than that of said conductive line.

14. The communication equipment according to Claim 10, wherein said interdigital capacitor has a width greater than that of said conductive line.

15. The communication equipment according to Claim 10, wherein said interdigital capacitor is coated with a resist film constructed of an insulator.

16. The communication equipment according to Claim 10, wherein a microstripline including a ground conductor formed on another surface of said dielectric substrate is constructed.

17. The communication equipment according to Claim 10, wherein a coplanar line including a ground conductor formed on the surface of said dielectric substrate is constructed.

18. The communication equipment according to Claim 10, wherein a grounded coplanar line including two ground conductors respectively formed on the surface and another surface of said dielectric substrate is constructed.

19. The communication equipment according to Claim 10, comprising a multiplexing circuit, as said first electric circuit, that outputs an electrical signal to said DC block circuit, and an EA modulator, as said second electric circuit, that generates an intensity-modulated optical signal from a continuous wave optical signal according to the electrical signal applied thereto by way of said DC block circuit.

20. The communication equipment according to Claim 10, comprising a photo diode with a preamplifier, as said first electric circuit, for converting an intensity-modulated optical signal applied thereto into an amplitude-modulated electrical signal, and a demultiplexer, as said second electric circuit, for demultiplexing the amplitude-modulated electrical signal.